

ABSTRACT OF THE DISCLOSURE

A printed wiring substrate 1 includes a core substrate 2 having a front surface 3 and a back surface 4 and an chip capacitor 10 serving as an electronic component embedded via a resin 13 in a through-hole 5 extending
5 through the core substrate between the front surface 3 and the back surface 4. The chip capacitor 10 has an electrode 12 projecting from the upper and lower ends thereof. The resin 13 contains silica filler (inorganic filler) f. The maximum particle size d of the silica filler f is not greater than half the height h of the electrode 12.